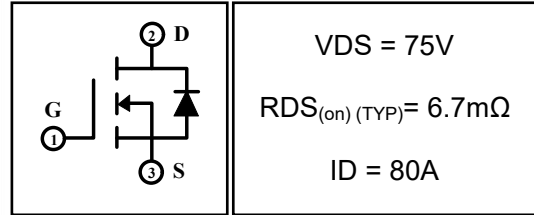


80A 75V N-channel Enhancement Mode Power MOSFET

1 Description

These N-channel enhancement mode power MOSFETS Used advanced trench technology design, provided excellent RDS(on) and low gate charge. Which accords with the RoHS standard.



2 Features

- Low On Resistance
- Low Gate Charge
- Fast Switching
- Low Reverse Transfer Capacitances
- 100% Single Pulse Avalanche Energy Test
- 100% ΔVDS Test

3 Applications

- AC-DC Switching Power
- Brushless Electric Machine
- High Power Charger
- Inverter
- Electric Tool
- Balance Car
- Controller for Electric Vehicles



4 Electrical Characteristics

4.1 Absolute Maximum Ratings (Tc=25°C, unless otherwise noted)

Parameter	Symbol	Value		Units
		D7509/ID7509/ED7509	FD7509	
Drain-Source Voltage	V _{DS}	75		V
Gate-Source Voltage	V _{GS}	±25		V
Drain Current(continuous) ^(Note 3)	I _D	80		A
Drain Current(continuous)(T=100°C) ^(Note 3)	I _D (100°C)	65		A
Drain Current(Pulsed) ^(Note 4)	I _{DM}	320		A
Avalanche Current ^(Note 5)	I _{AS}	25		A
Single Pulse Avalanche Energy ^(Note 5)	E _{AS}	525		mJ
Maximum Power Dissipation	T _a =25°C	P _{tot}	2	W
	T _c =25°C	P _{tot}	210	85
Operating Junction Temperature Range	T _j	-55~175		°C
Storage Temperature Range	T _{stg}	-55~175		°C
High Temperature(tin solder)	T _L	300		°C

4.2 Thermal Characteristics

Parameter	Symbol	Value		Unit
		D7509/ID7509/ED7509	FD7509	
Thermal Resistance, Junction to Case-sink	R _{thJC}	0.71	1.76	°C/W
Thermal Resistance, Junction to Ambient	R _{thJA}	75	75	°C/W

4.3 Electrical Characteristics (Tc=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Max	
Off Characteristics						
Drain-source Breakdown Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	75	81	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =75V, V _{GS} =0V, T _C =25°C	--	--	1	μA
		V _{DS} =60V, V _{GS} =0V, T _C =125°C	--	--	100	μA
Gate-to-Body Leakage Current	I _{GSS}	V _{GS} =±25V, V _{DS} =0V	--	--	±100	nA
On Characteristics (Note 3)						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Drain-source on Resistance	R _{DS(on)}	V _{GS} =10V, I _D =40A	--	6.7	9	mΩ
Dynamic Characteristics (Note 4)						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =25V, f=1.0MHz	--	4286	--	pF
Output Capacitance	C _{oss}		--	373	--	
Reverse Transfer Capacitance	C _{rss}		--	280	--	
Gate Resisitance	R _G	V _{DD} =0V, V _{GS} =0V, F=1MHz	--	1.3	--	Ω
Switching Characteristics (note4)						
Turn-on Delay Time	t _{d(on)}	I _D =40A, V _{DD} =37.5V, V _{GS} =10V, R _{GEN} =6Ω	--	25	--	nS
Turn-on Rise Time	t _r		--	42	--	
Turn-off Delay Time	t _{d(off)}		--	62	--	
Turn-off Fall Time	t _f		--	19	--	
Total Gate Charge	Q _g	I _D =40A, V _{DD} =60V, V _{GS} =10V	--	108	--	nC
Gate-to-Source Charge	Q _{gs}		--	21	--	
Gate-to-Drain("Miller") Charge	Q _{gd}		--	40	--	
Drain-Source Diode Characteristics						
Diode Forward Voltage ⁽³⁾	V _{SD}	V _{GS} =0V, I _S =40A	--	--	1.3	V
Diode Forward Current ⁽²⁾	I _S		--	--	80	A
Reverse Recovery Time	t _{rr}	T _J =25°C, I _F =40A, dI _F /dt=100A/μS, V _{GS} =0V	--	62	--	nS
Reverse Recovery Charge	Q _{rr}		--	127	--	nC

Notes:

- 1: Repetitive rating, pulse width limited by maximum junction temperature.
- 2: Surface mounted on FR4 Board, t≤10sec.
- 3: Pulse width ≤ 300μs, duty cycle ≤ 2%.
- 4: Guaranteed by design, not subject to production.
- 5: L=0.5mH, I_D=46A, V_{DD}=50V, V_{GATE}=75V, Start T_J=25°C.

5 Typical characteristics diagrams

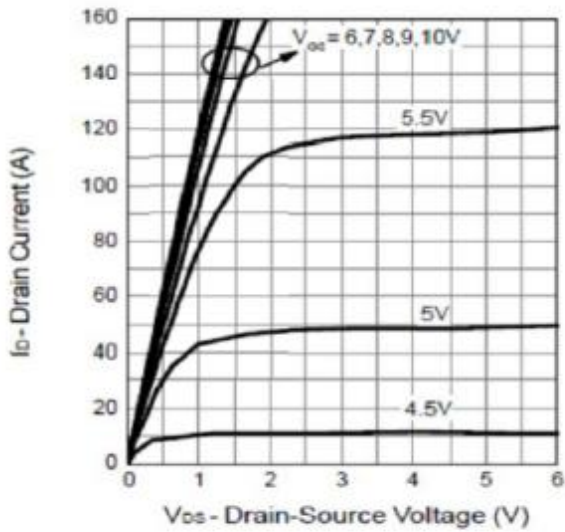


Figure 1 Output Characteristics

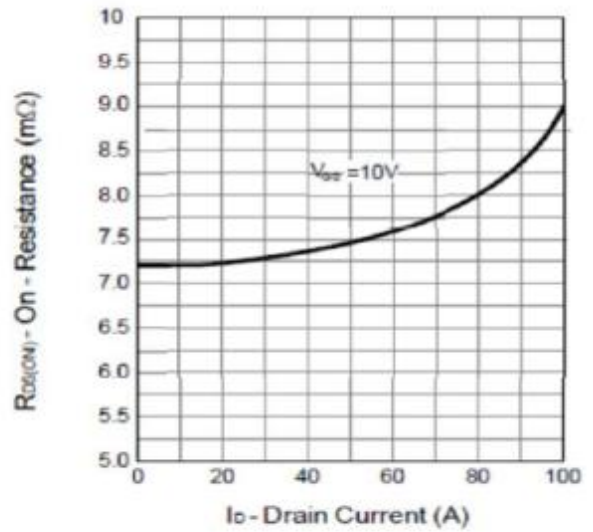


Figure 2 Drain-Source On Resistance

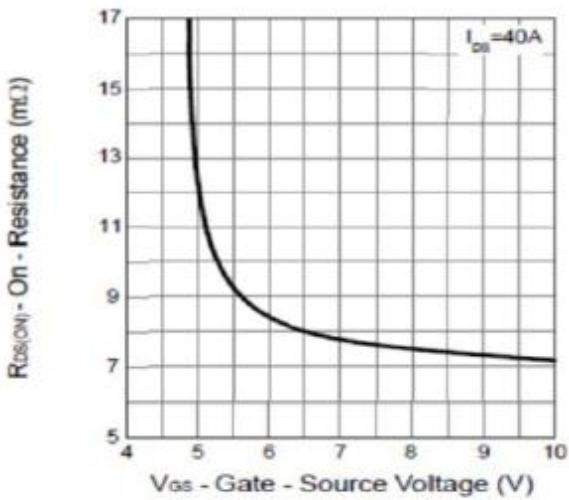


Figure 3 Drain-Source On Resistance

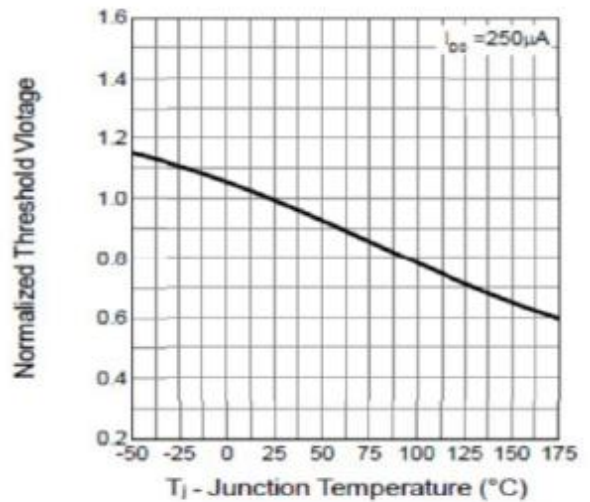


Figure 4 Gate Threshold Voltage

5 Typical characteristics diagrams(continues)

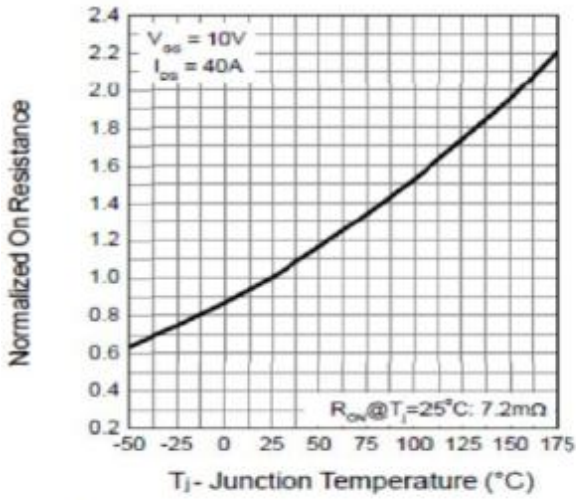


Figure 5 Drain-Source On Resistance

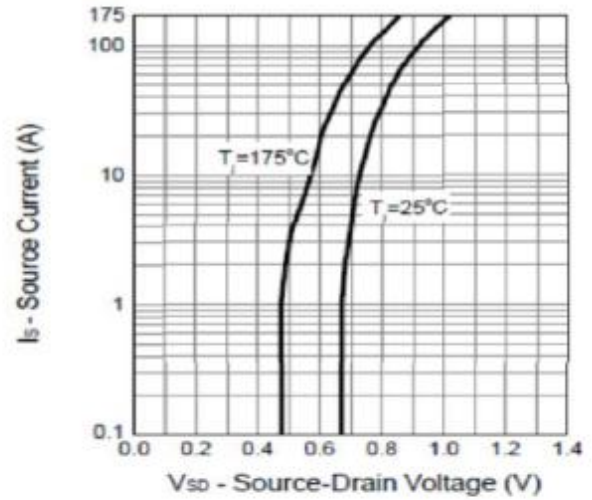


Figure 6 Source-Drain Diode Forward

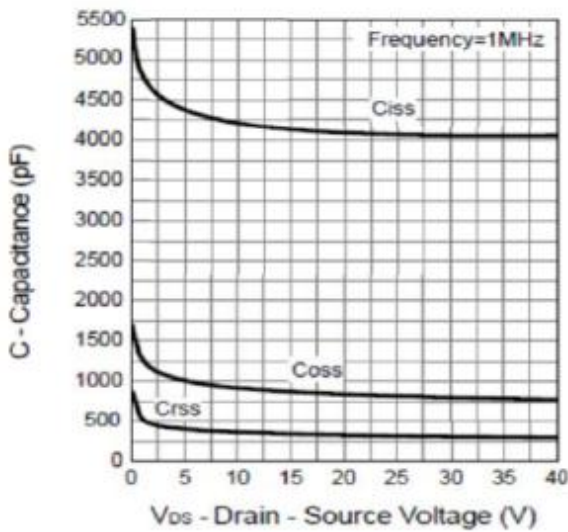


Figure 7 Capacitance

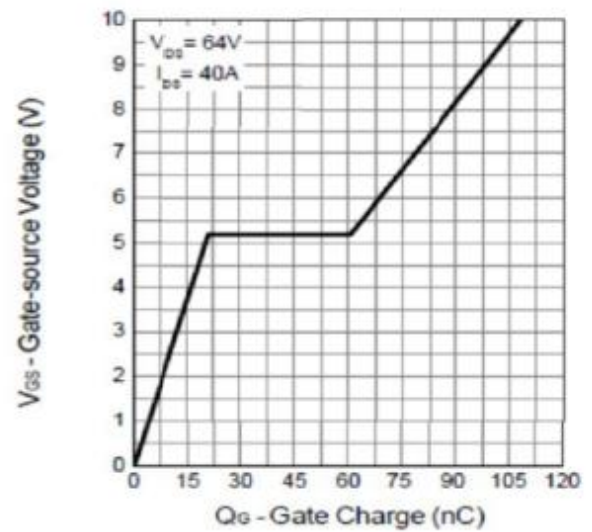


Figure 8 Gate Charge

5 Typical characteristics diagrams(continues)

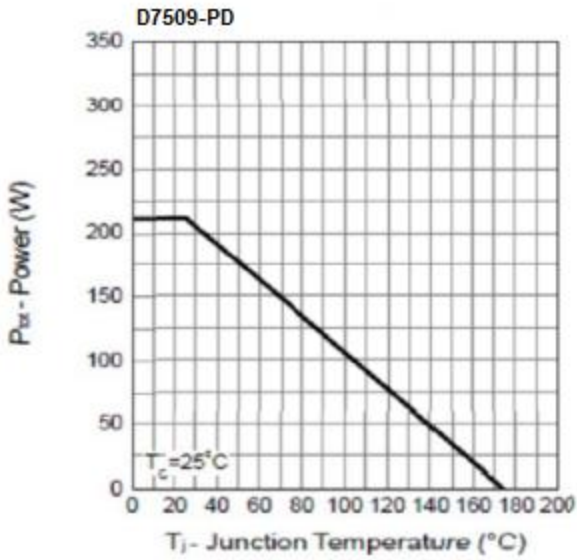


Figure 9 Power Dissipation

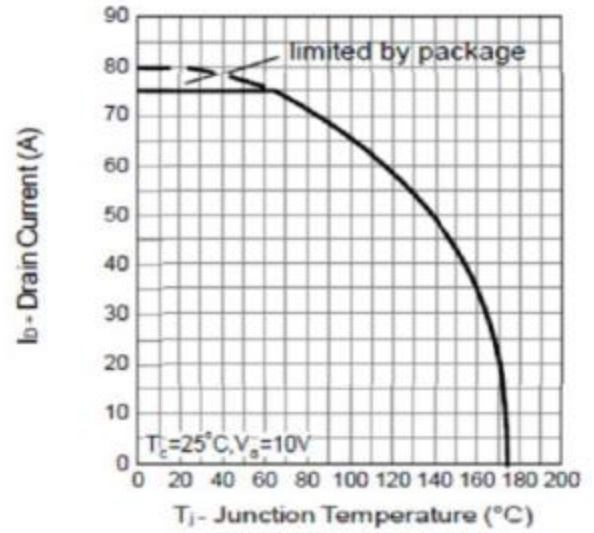


Figure 10 Drain Current

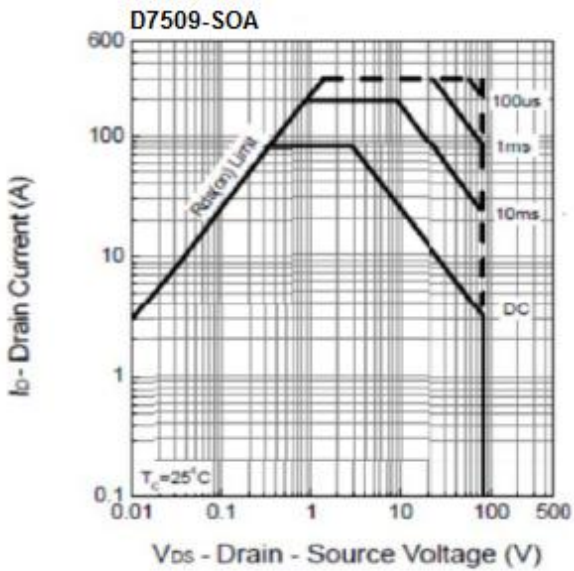


Figure 11 Safe Operation Area

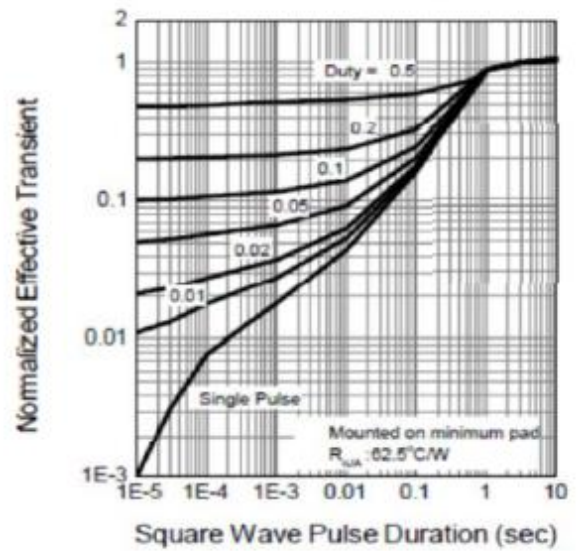


Figure 12 Thermal Transient Impedance

5 Typical characteristics diagrams(continues)

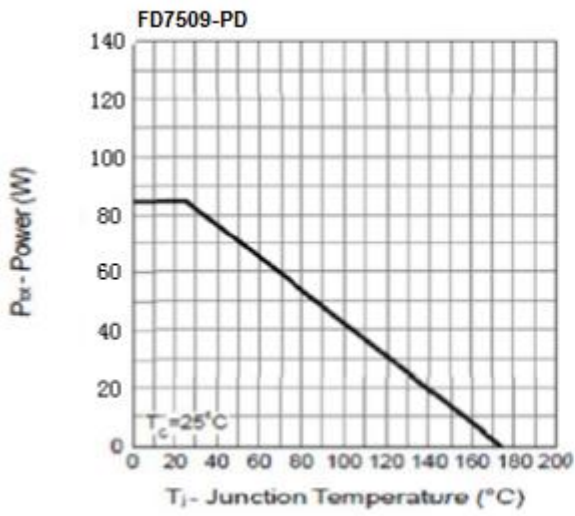


Figure 13 Power Dissipation

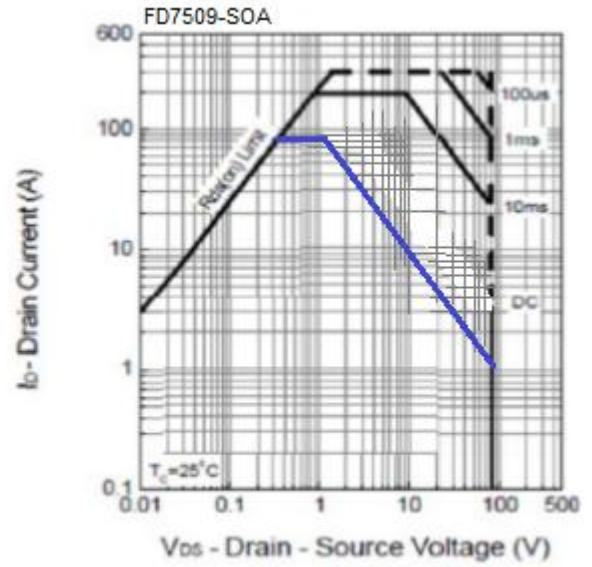
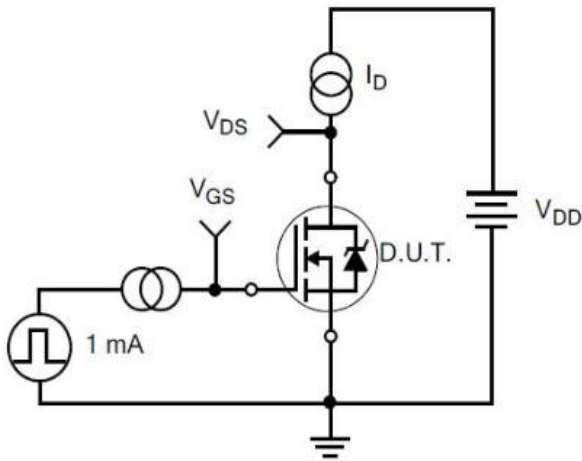
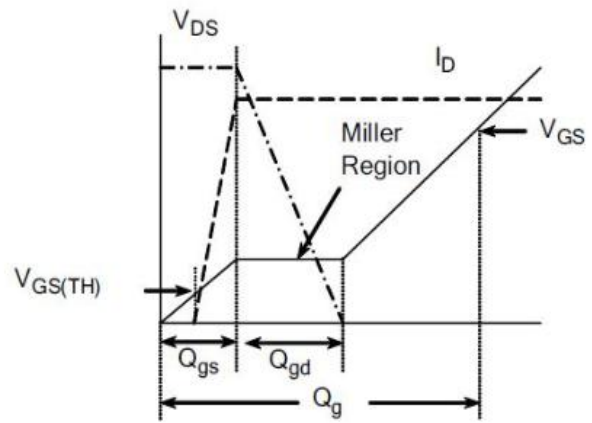


Figure 14 Safe Operation Area

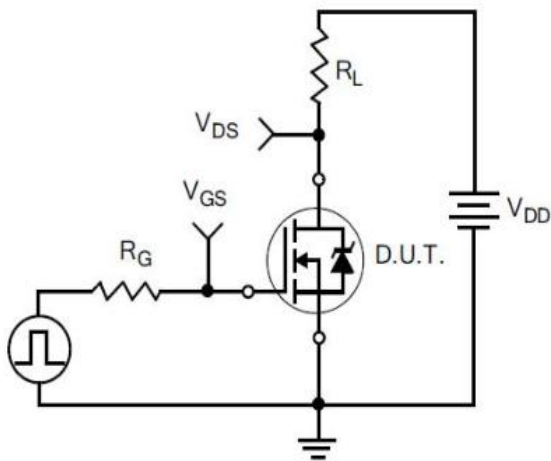
6 Typical Test Circuit and Waveform



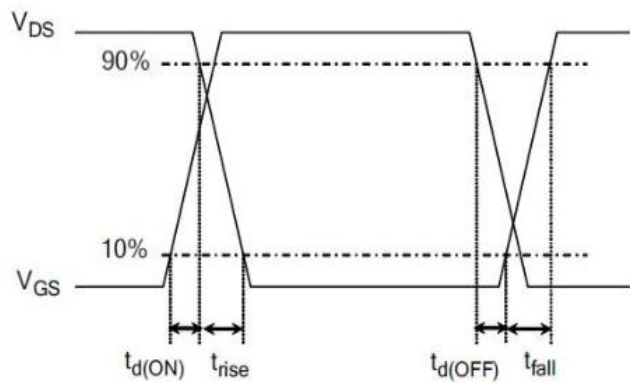
1) Gate Charge Test Circuit



2) Gate Charge Waveform

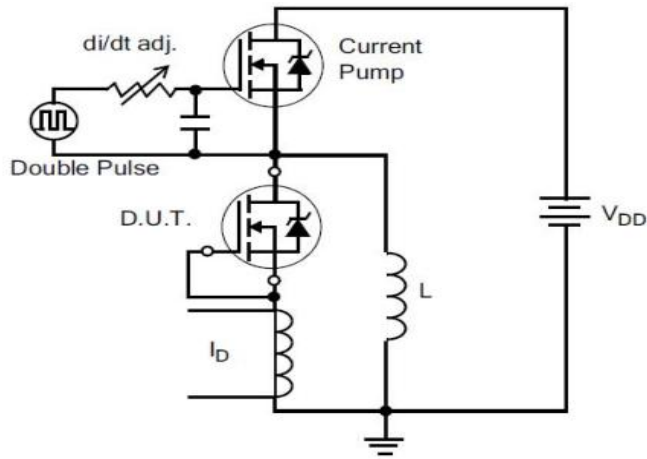


3) Resistive Switching Test Circuit

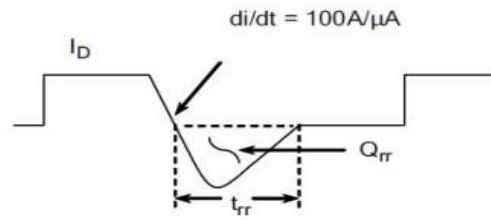


4) Resistive Switching Waveforms

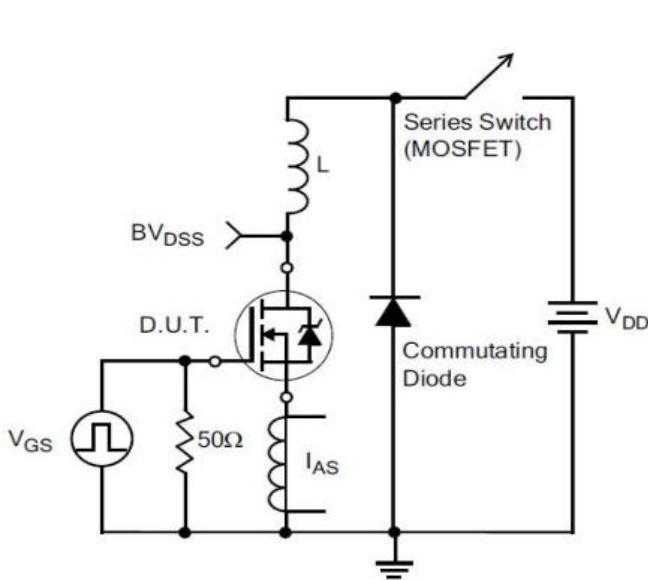
6 Typical Test Circuit and Waveform(continues)



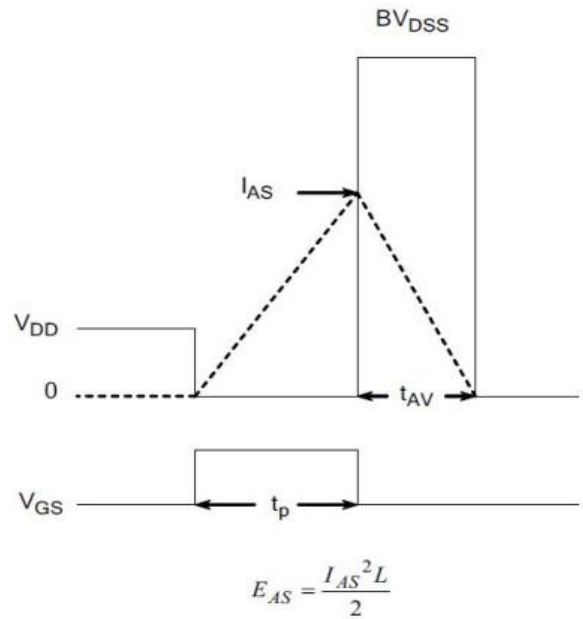
5) Diode Reverse Recovery Test Circuit



6) Diode Reverse Recovery Waveform

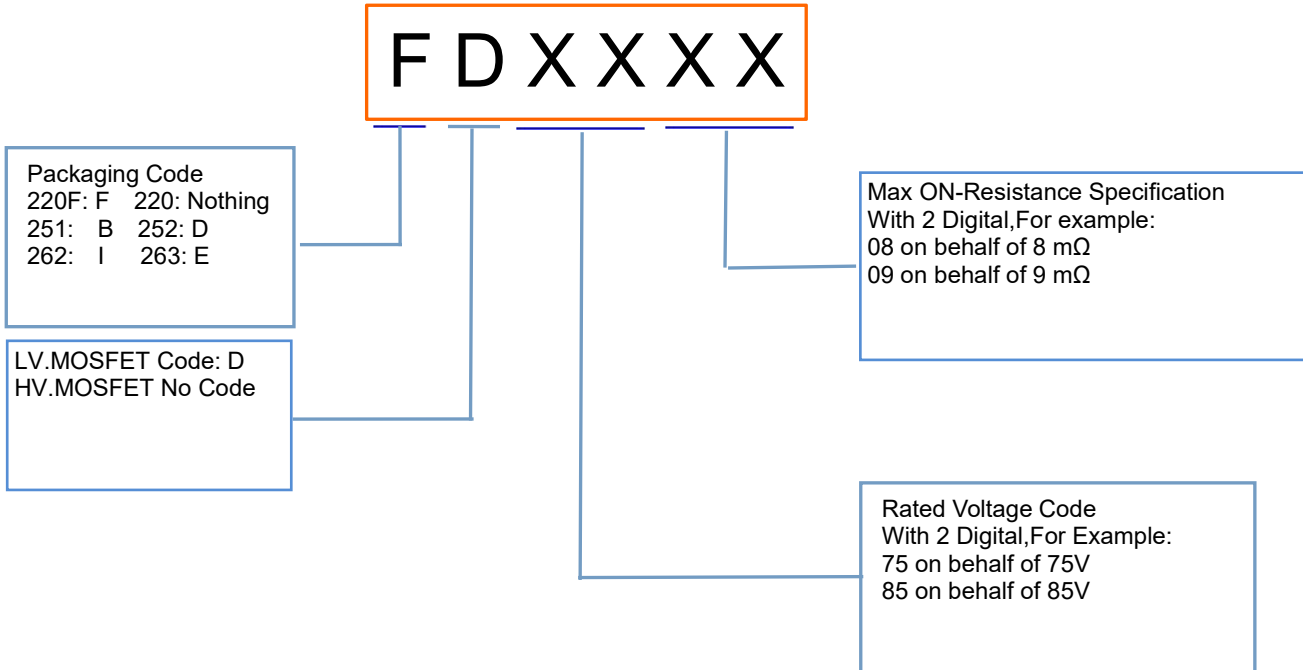


7) . Unclamped Inductive Switching Test Circuit



8) Unclamped Inductive Switching Waveforms

7 Product Names Rules

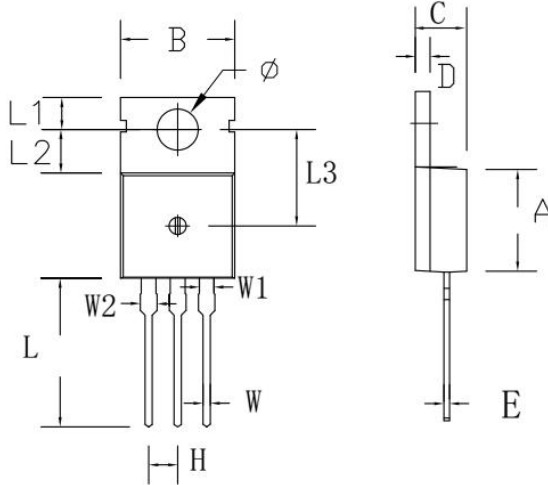


8 Product Specifications and Packaging Models

Product Model	Package Type	Mark Name	RoHS	Package	Quantity
D7509	TO-220C	D7509	Pb-free	Tube	1000/box
FD7509	TO-220F	FD7509	Pb-free	Tube	1000/box
ID7509	TO-262	ID7509	Pb-free	Tube	1000/box
ED7509	TO-263	ED7509	Pb-free	Tape & Reel	800/box

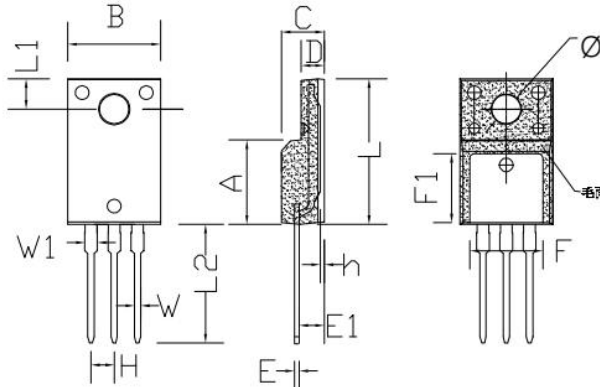
9 Dimensions

TO-220C PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20			0.057
E	0.40			0.024
H	2.54 TYP		0.100 TYP	
W	0.60			0.037
W1	1.05	1.45	0.041	0.057
W2	1.20	1.60	0.047	0.063
L	12.60	13.40	0.496	0.528
L1	2.45	2.95	0.096	0.116
L2	3.45	3.95	0.136	0.156
L3	8.15	8.65	0.321	0.341
Φ	3.50	3.90	0.138	0.154

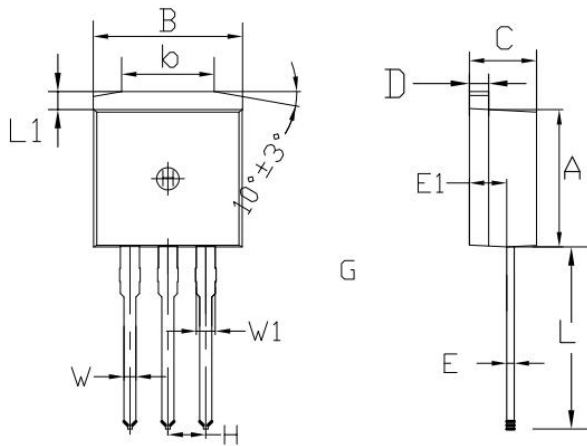
TO-220F PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	10.00	10.50	0.394	0.413
C	4.30	4.90	0.169	0.193
D	2.30	2.70	0.091	0.106
L	15.55	16.15	0.612	0.636
h	0.40	0.60	0.016	0.024
L1	3.15	3.55	0.124	0.140
L2	12.65	13.35	0.498	0.526
W	0.70	0.90	0.028	0.035
W1	1.15	1.55	0.045	0.061
H	2.54 TYP		0.100 TYP	
E	0.48	0.53	0.019	0.021
Φ	2.90	3.40	0.114	0.134
E1	2.40	2.90	0.094	0.114
F	7.75	8.25	0.305	0.325
F1	7.35	7.85	0.289	0.309

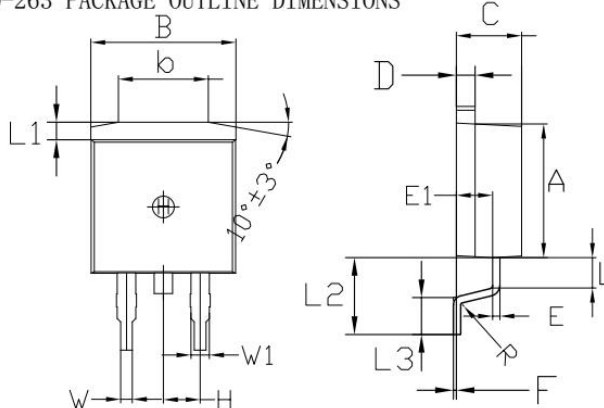
9 Dimensions(continues)

TO-262 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
L	12.25	13.75	0.482	0.541
L1	1.15	1.45	0.045	0.057
E1	2.4	2.6	0.0945	0.1024
W	0.80	0.82	0.0315	0.034
W1	1.20	1.30	0.047	0.051
H	2.54 TYP		0.200 TYP	
b	5.50	6.50	0.216	0.256

TO-263 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
L	1.90	2.30	0.075	0.091
L1	1.15	1.45	0.045	0.057
R	0.24	0.26	0.0095	0.0102
W	0.80	0.82	0.0315	0.0323
W1	1.20	1.30	0.047	0.051
H	2.54 TYP		0.200 TYP	
b	5.50	6.50	0.216	0.256
E1	2.4	2.6	0.0946	0.1024
L2	5.20	5.80	0.205	0.228
L3	2.20	3.20	0.087	0.126
F	0.03	0.23	0.0012	0.0091

10 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

11 Appendix

Revision history:

Date	REV.	Description	Page
2017.03.09	1.0	Original	